



Material Content Data Sheet



Sales Product Name				IPZ40N04S5L-4R8		Issued		9. January 2019	
MA#				MA001727520					
Package				PG-TSDSON-8-32		Weight*		35.36 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.346	0.98	0.98	9786	9786	
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		88		
	non noble metal	zinc	7440-66-6	0.012	0.04		352		
	non noble metal	iron	7439-89-6	0.249	0.70		7036		
wire	non noble metal	copper	7440-50-8	10.102	28.57	29.32	285711	293187	
	noble metal	gold	7440-57-5	0.029	0.08	0.08	821	821	
	organic material	carbon black	1333-86-4	0.037	0.11		1053		
encapsulation	plastics	epoxy resin	-	1.917	5.42		54217		
	inorganic material	silicondioxide	60676-86-0	16.657	47.11	52.64	471107	526377	
leadfinish	non noble metal	tin	7440-31-5	0.400	1.13	1.13	11320	11320	
plating	noble metal	silver	7440-22-4	0.086	0.24	0.24	2422	2422	
solder	non noble metal	tin	7440-31-5	0.011	0.03		298		
	noble metal	silver	7440-22-4	0.013	0.04		372		
	non noble metal	lead	7439-92-1	0.503	1.42	1.49	14218	14888	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		17		
	non noble metal	zinc	7440-66-6	0.002	0.01		66		
	non noble metal	iron	7439-89-6	0.047	0.13		1329		
	non noble metal	copper	7440-50-8	1.908	5.40	5.54	53952	55364	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		26		
	non noble metal	zinc	7440-66-6	0.004	0.01		103		
	non noble metal	iron	7439-89-6	0.073	0.21		2060		
	non noble metal	copper	7440-50-8	2.958	8.36	8.58	83646	85835	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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